

Specification of Thermoelectric Module

TEC1-12722

Description

The 127 couples, 40 mm × 40 mm size module is made of selected high performance ingot to achieve superior cooling performance and greater delta T up to 70 °C, designed for superior cooling and heating up to 100/200 °C applications. If higher operation or processing temperature is required, please specify, we can design and manufacture the custom made module according to your special requirements.

Features

- High effective cooling and efficiency.
- No moving parts, no noise, and solid-state
- Compact structure, small in size, light in weight
- Environmental friendly, RoHS compliant
- Precise temperature control
- Exceptionally reliable in quality, high performance
- Sustain million thermal cycles with 70 °C temperature change range

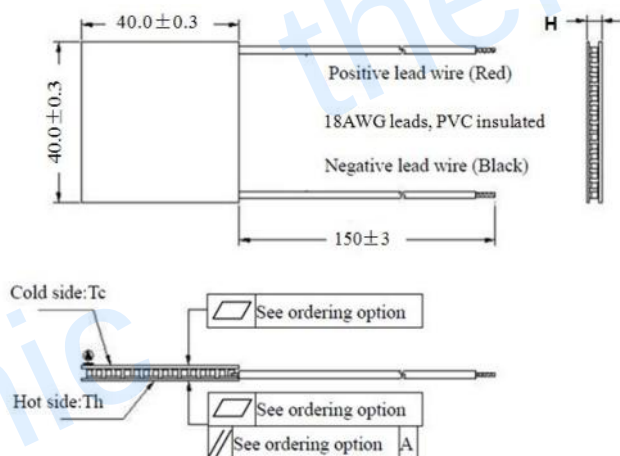
Application

- Food and beverage service refrigerator
- Portable cooler box for cars
- Temperature stabilizer
- Liquid cooling
- CPU cooler and scientific instrument
- Photonic and medical systems

Performance Specification Sheet

Th (°C)	27	50	Hot side temperature at environment: dry air, N ₂
DT _{max} (°C)	70	79	Temperature Difference between cold and hot side of the module when cooling capacity is zero at cold side
U _{max} (Voltage)	16	17.2	Voltage applied to the module at DT _{max}
I _{max} (amps)	18.5	18.5	DC current through the modules at DT _{max}
Q _{Cmax} (Watts)	185.3	202.5	Cooling capacity at cold side of the module under DT=0 °C
AC resistance (ohms)	0.68	0.74	The module resistance is tested under AC
Tolerance (%)	± 10		For thermal and electricity parameters

Geometric Characteristics Dimensions in millimeters



Ordering Option

Suffix	Thickness H (mm)	Flatness/ Parallelism (mm)	Lead wire length(mm) Standard/Optional length
TF	0:3.0±0.1	0: 0.08/0.08	150 ± 3 / Specify
TF	1:3.0±0.03	1: 0.03/0.03	150 ± 3 / Specify

Eg. TF01: Thickness 3.0 ± 0.1 (mm) and Flatness 0.03/0.03 (mm)

Manufacturing Options

A. Solder:

1. T100: BiSn (Tmelt=138°C)
2. T200: CuAgSn (Tmelt = 217°C)
3. T240: SbSn (Tmelt = 240°C)

B. Sealant:

1. NS: No sealing (Standard)
2. SS: Silicone sealant
3. EPS: Epoxy sealant

C. Ceramics:

1. Alumina (Al₂O₃, white 96%)
2. Aluminum Nitride (AlN)

D. Ceramics Surface Options:

1. Blank ceramics (not metalized)
2. Metalized

Naming for the Module

TEC1-12722- X-X-X-X



TEC1-12722-T100-NS-TF01-AIO

T100: BiSn (Tmelt=138°C)

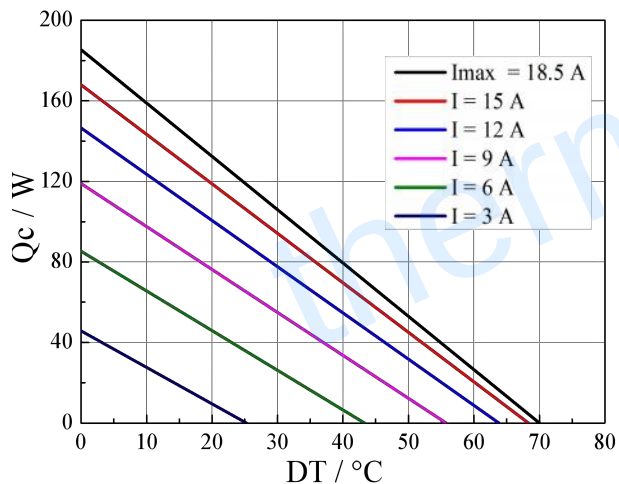
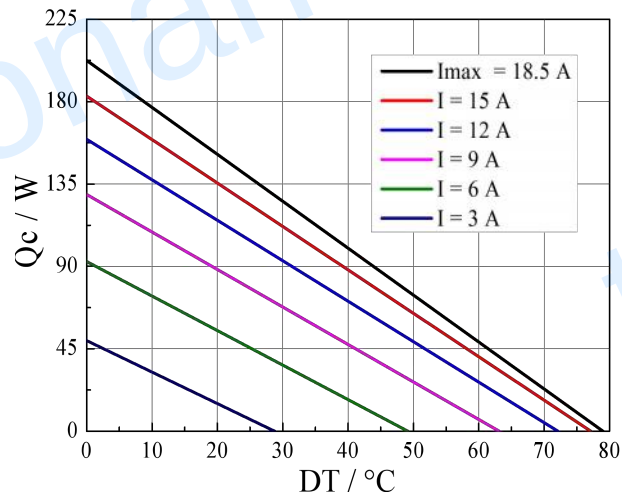
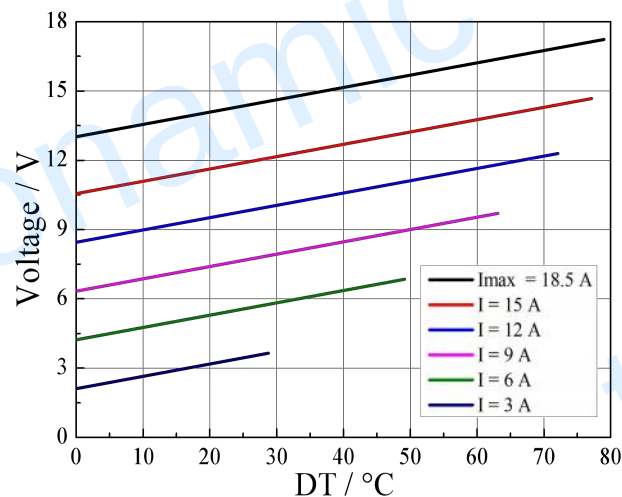
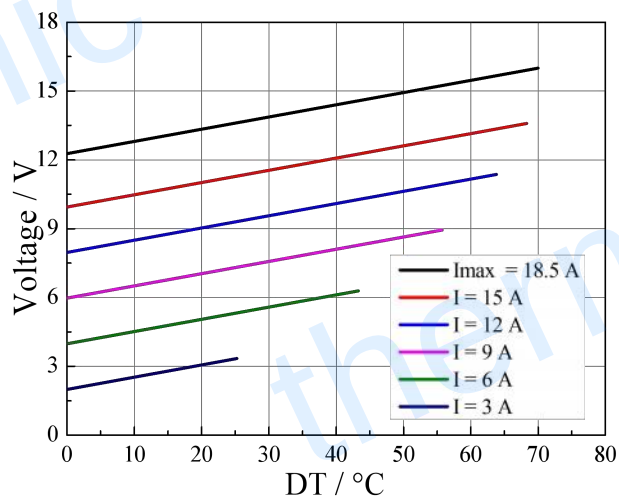
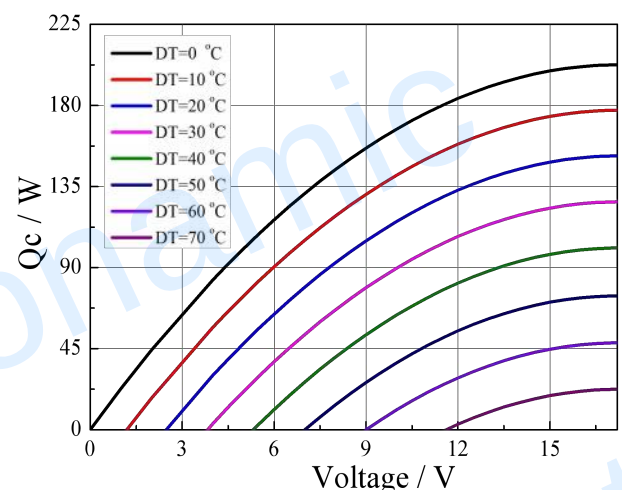
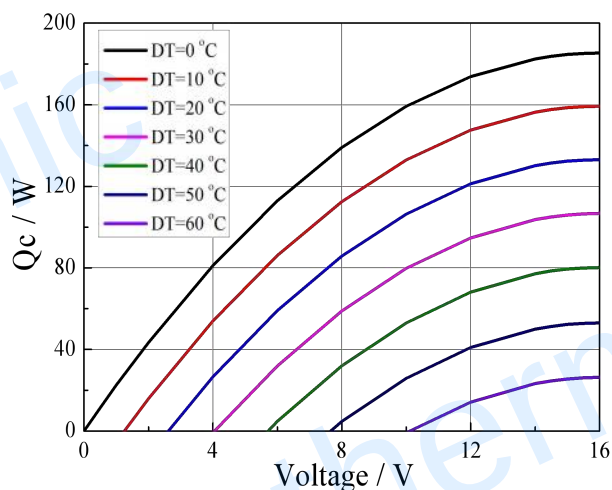
NS: No sealing

AIO: Alumina (Al₂O₃, white 96%)

TF01: Thickness ±0.1(mm) and Flatness/Parallelism 0.025/0.025 (mm)

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Performance Curves at $T_h=27\text{ }^{\circ}\text{C}$ Performance Curves at $T_h=50\text{ }^{\circ}\text{C}$ Standard Performance Graph $Q_c = f(DT)$ Standard Performance Graph $V = f(\Delta T)$ Standard Performance Graph $Q_c = f(V)$

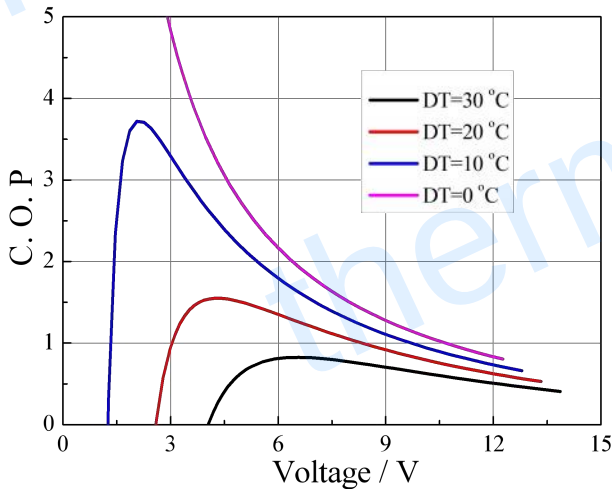
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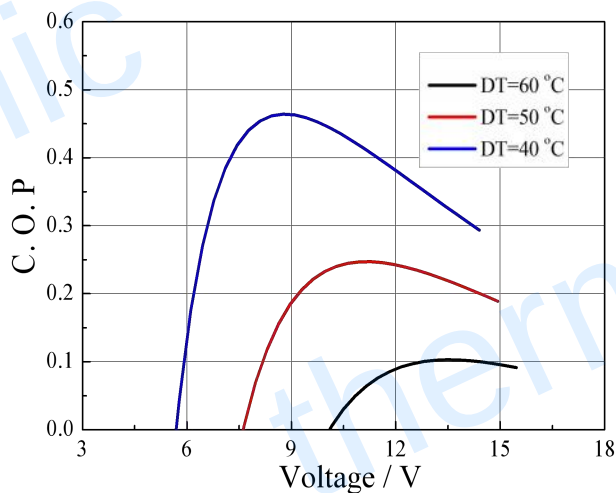
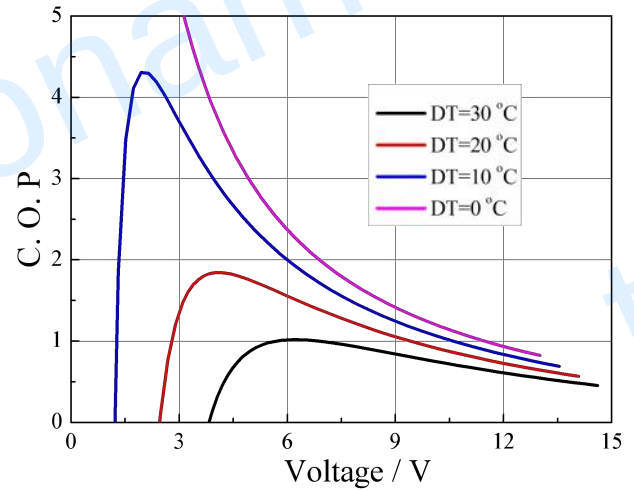
TEC1-12722

Performance Curves at $T_h=27^\circ\text{C}$

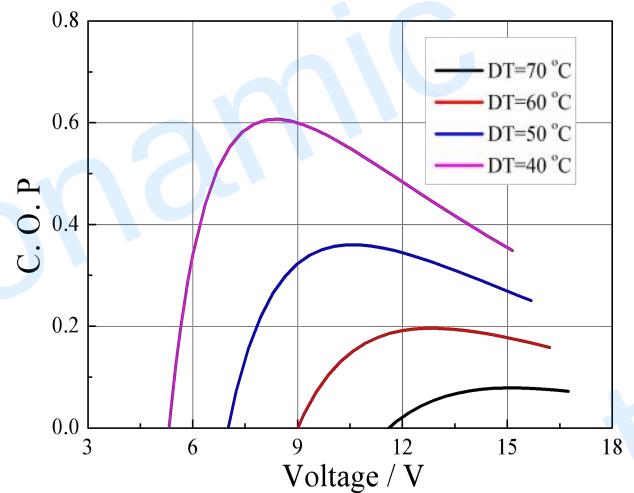


Standard Performance Graph $\text{COP} = f(V)$ of ΔT ranged from 0 to 30°C

Performance Curves at $T_h=50^\circ\text{C}$



Standard Performance Graph $\text{COP} = f(V)$ of ΔT ranged from 40 to 60/70 $^\circ\text{C}$



Remark: The coefficient of performance (COP) is the cooling power Q_c /Input power ($V \times I$).

Operation Cautions

- Attach the cold side of module to the object to be cooled
- Attach the hot side of module to a heat radiator for heat dissipating
- Operation below $I_{\max}$ or $V_{\max}$
- Work under DC

Note: All specifications subject to change without notice.